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Atty. Docket No. 8048-1014

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#4A

In re application of

Kazuto KADOKAWA

Confirmation No. 2717

Serial No. 09/995,591

GROUP 1775

Filed November 29, 2001

Examiner Jason L. Savage

PART

AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313

Sir:

Responsive to the Official Action of March 20, 2003,  
please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 1, replace the paragraph, beginning on line 34,  
bridging pages 1 and 2, as follows:

--For example, Japanese Laid-Open Utility Model  
application No. 5-95092 discloses the attachment manner of a heat  
radiating plate that offers improved soldering reliability when  
the soldering iron is used. This heat radiating plate is shown  
in FIG. 4. As shown, the heat radiating plate 2 has engaging  
portions 2a which are inserted into the attachment holes 1a of  
the printed wiring board 1, and small holes 2b are formed on the  
heat radiating plate 2 near the engaging portions 2a. With the  
heat radiating plate 2 thus configured, when the engaging  
portions 2a are heated by the soldering iron, the small holes 2b

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